

PTG6005B



N-Channel Enhancement Mode Trench Power MOSFET

Voltage:	60	Volts	Current:	5	Ampers	Package:	SOT-89
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Features

- NH'S Advanced Trench Technology
- Low Rds(on) For Low On-State Loss
- High EAS For High Reliability
- Excellent Qg*Rds(on) Product(FOM)

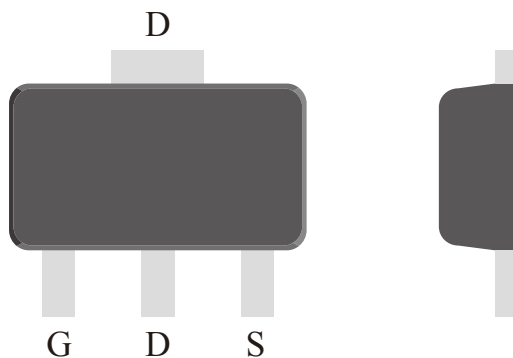
Typical Applications

- DC-DC Converter
- Battery Management System(BMS)
- Printed Circuit Board For Control Circuit
- Uninterruptible Power Supplies(UPS)

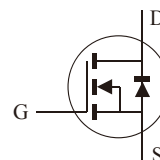
Product Summary

VDS Min.@Tj	60	V
ID Min.@Ta	5	A
RDS(ON)(TYP)@10V	25	mΩ

Diagram:



Polarity:



***100% UIS TESTED**

***100% ΔVDS TESTED**

Absolute Maximum Ratings (Ta=25℃ Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Ratings	Unit
Drain-Source Voltage		V _{DS}	60	V
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current (Note 1)	Ta= 25 ℃	I _D	5	A
	Ta= 100 ℃		3	
Drain Current-Pulse (Note 1)	Tj< 150 ℃	I _{DM}	20	A
Maximum Power Dissipation Power	Ta= 25 ℃	P _D	1800	mW
Dissipation Derating Factor Above 25℃	Ta= 100 ℃		720	
Derating Factor		D _F	14.40	mW/℃

Thermal Characteristics (Ta=25℃ Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Typ.	Unit
Junction Temperature		T _J	-55 to 150	℃
Storage Temperature Range		T _{STD}	-55 to 150	℃
Thermal Resistance Junction To Ambient With Steady-State	Still Air Environment With Ta=25℃	R _{θJA}	69.4	℃/W

Notes: 1.Pulse Width Limited By Max. Junction Temperature. (See Fig. 13).

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Electrical Characteristics (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Min.	Typ.	Max.	Unit
Static Off Characteristics						
Drain-Source Breakdown Voltage	VGS=0V,ID=250uA	BV _{DSS}	60	--	--	V
Bvdss Temperature Coefficient	ID=250uA,Reference25℃	ΔBV _{DSS} /ΔT _J	--	0.07	--	V/℃
Drain-Source Leakage Current	VDS= 60 V,VGS=0V	I _{DSS}	--	--	1	uA
Gate-Body Leakage Current	VGS= ±20 V,VDS=0V	I _{GSS}	--	--	±100	nA
Static On Characteristics						
Gate Threshold Voltage	VGS= VDS ID=250uA	V _{GS(TH)}	1.0	1.8	2.5	V
Drain-Source On Resistance	ID= 2.5 A,VGS= 10.0 V	R _{DS(ON)}	--	25	35	mΩ
	ID= 2.5 A,VGS= 4.5 V		--	33	46	
Dynamic Characteristics						
Input Capacitance	VDS= 30 V	C _{iss}	--	990.0	--	pF
Output Capacitance	VGS= 0 V	C _{oss}	--	52.0	--	pF
Reverse Transfer Capacitance	F= 1 MHZ	C _{rss}	--	45.0	--	pF
Switching Paramters (Test Circuit & Waveform See Fig.14)						
Turn-On Delay Time	VDS= 30 V	t _{d(on)}	--	9.5	--	ns
Turn-On Rise Time	VGS= 10.0 V	t _r	--	9.7	--	ns
Turn-Off Delay Time	RG= 10.0 Ω	t _{d(off)}	--	40.0	--	ns
Turn-Off Rise Time		t _f	--	5.5	--	ns
Gate Charge Paramters (Test Circuit & Waveform See Fig.15)						
Total Gate Charge	VDS= 30 V	Q _g	--	25.0	--	nC
Gate-Source Charge	VGS= 10.0 V	Q _{gs}	--	5.0	--	nC
Gate-Drain Charge	ID= 2.5 A	Q _{gd}	--	6.0	--	nC
Drain-Source Diode Characteristics And Maximum Ratings (Test Circuit & Waveform See Fig.17)						
Max. Diode Forward Cuurent		I _S	--	--	5.0	A
Max. Pulsed Forward Cuurent		I _{SM}	--	--	20.0	A
Diode Forward Voltage	ID= 2.5 A,VGS=0V	V _{SD}	--	0.7	1.2	V

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Typical Characteristics Curves

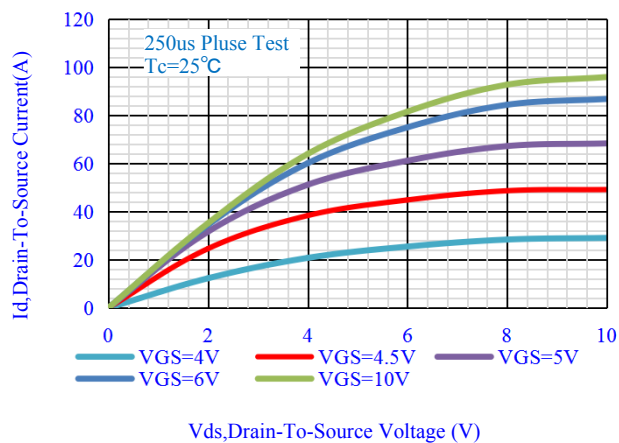


Fig.1-Output Characteristics

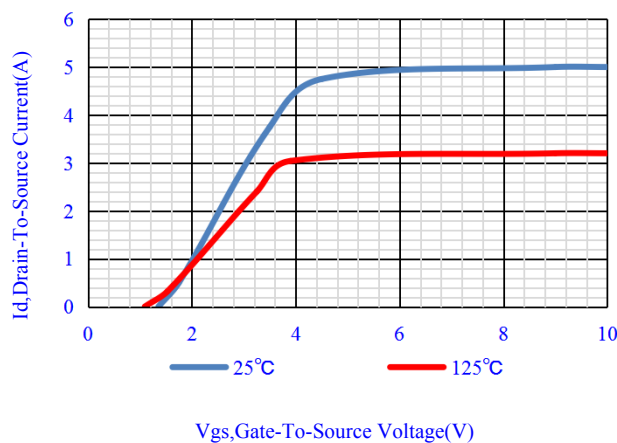


Fig.2-Transfer Characteristics

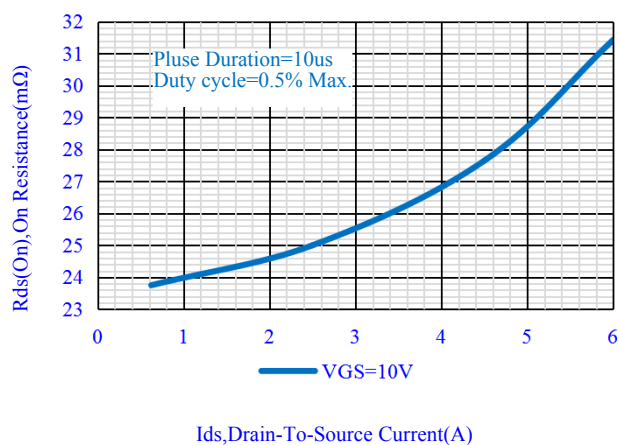


Fig.3-On Resistance Vs. Drain Current

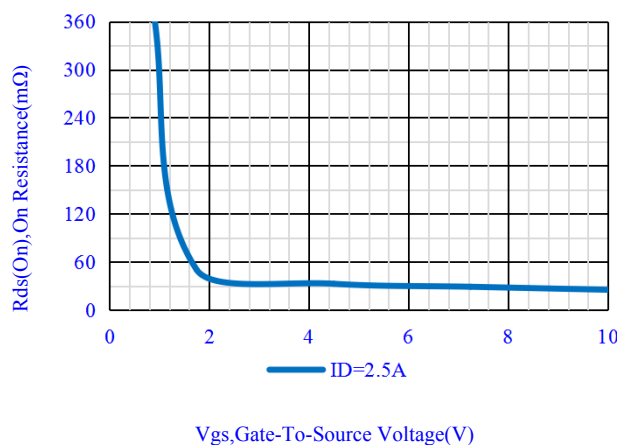


Fig.4-On Resistance Vs. Gate Source Voltage

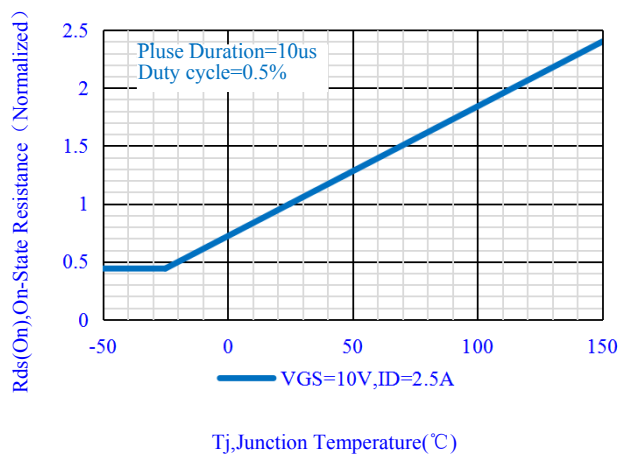


Fig.5-On Resistance Vs. Junction Temperature

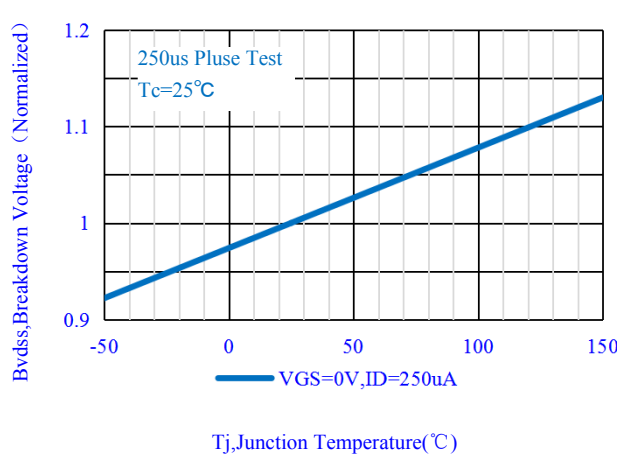


Fig.6-Breakdown Voltage Vs. Junction Temperature

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Typical Characteristics Curves

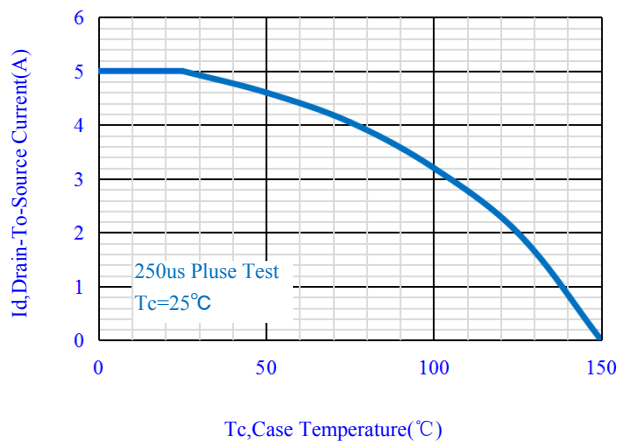


Fig.7-Maximum Continuous Drain Current Vs. Case Temperature

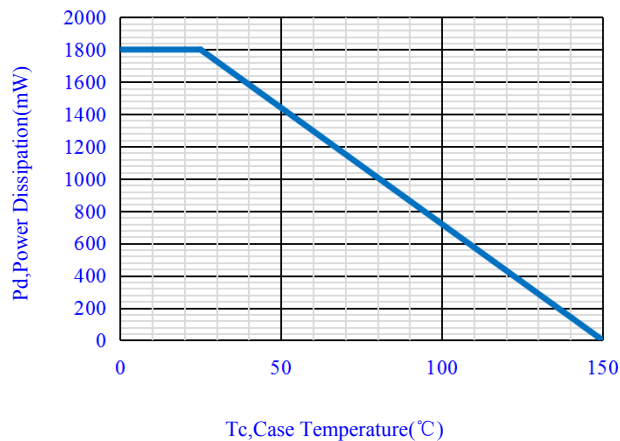


Fig.8-Maximum Power Dissipation Vs. Case Temperature

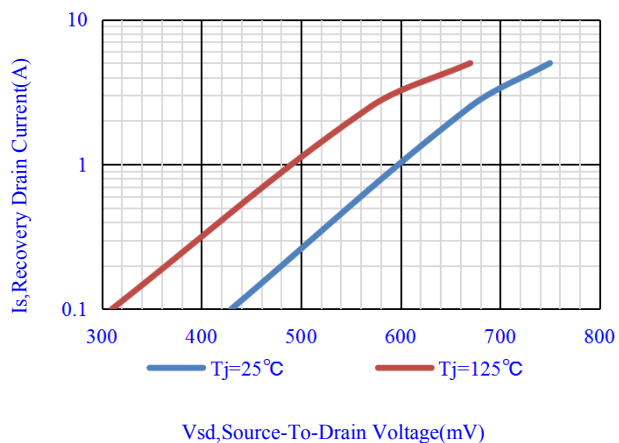


Fig.9-Source-To-Drain Diode Forward Voltage

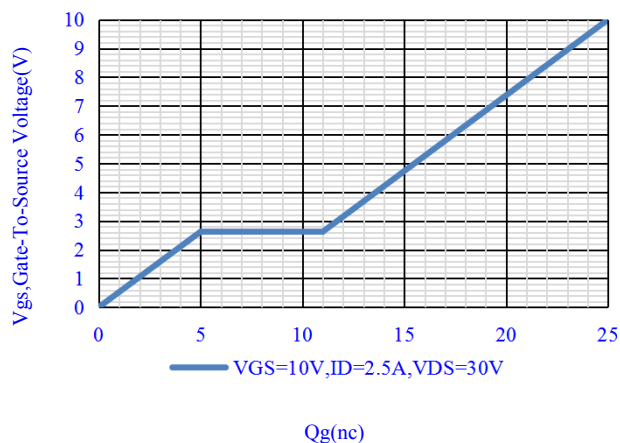


Fig.10-Gate Charge Waveform

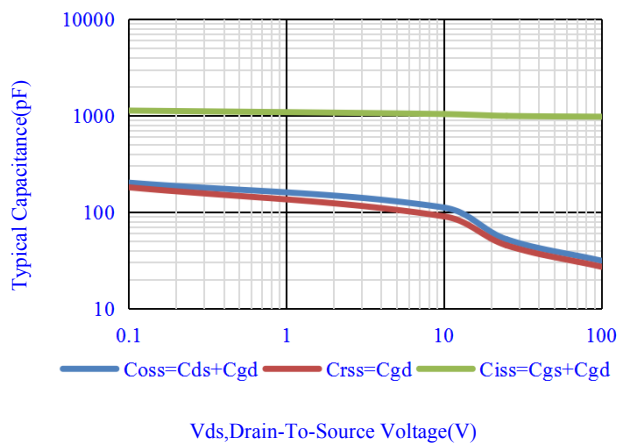


Fig.11-Typical Capacitance Vs. Drain-To-Source Voltage

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Typical Characteristics Curves

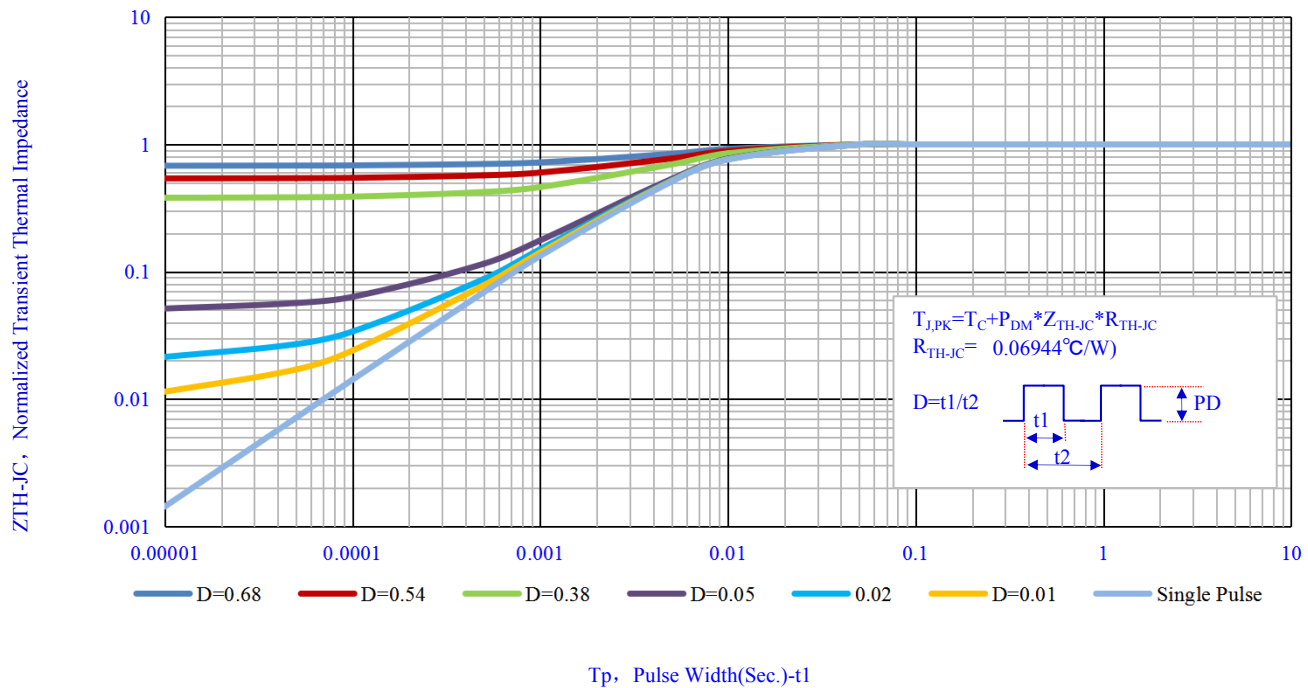


Fig.12- Normalized Maximum Transient Thermal Impedance Vs.Pulse Width

Test Circuit & Waveform

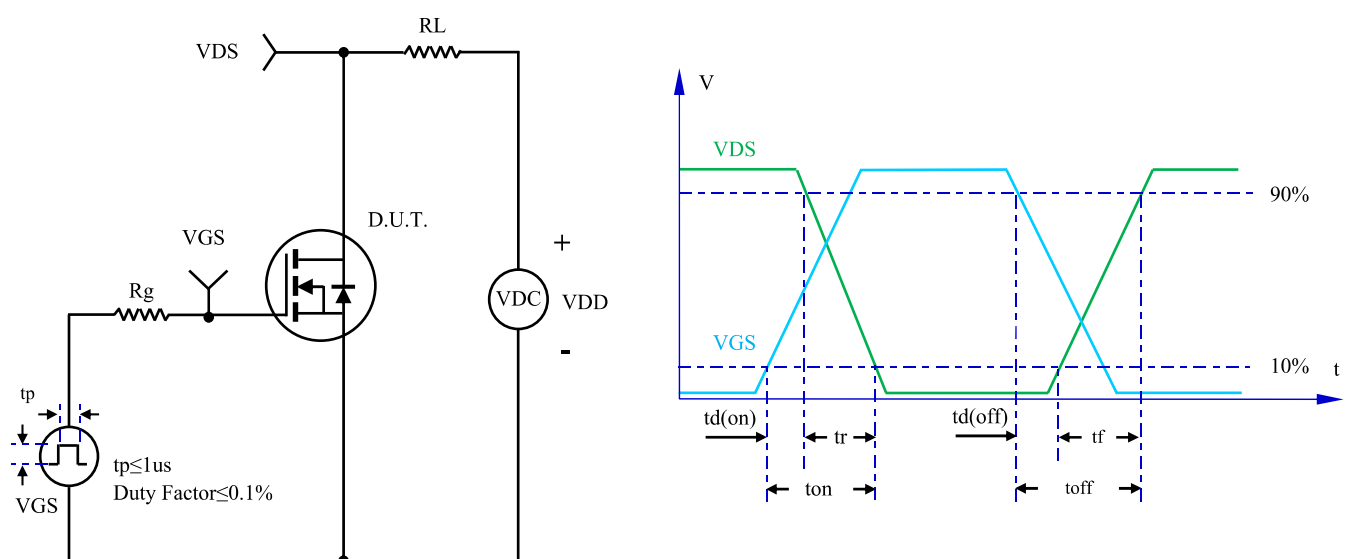


Fig.13- Resistive Switching Test Circuit & Waveform

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Test Circuit & Waveform

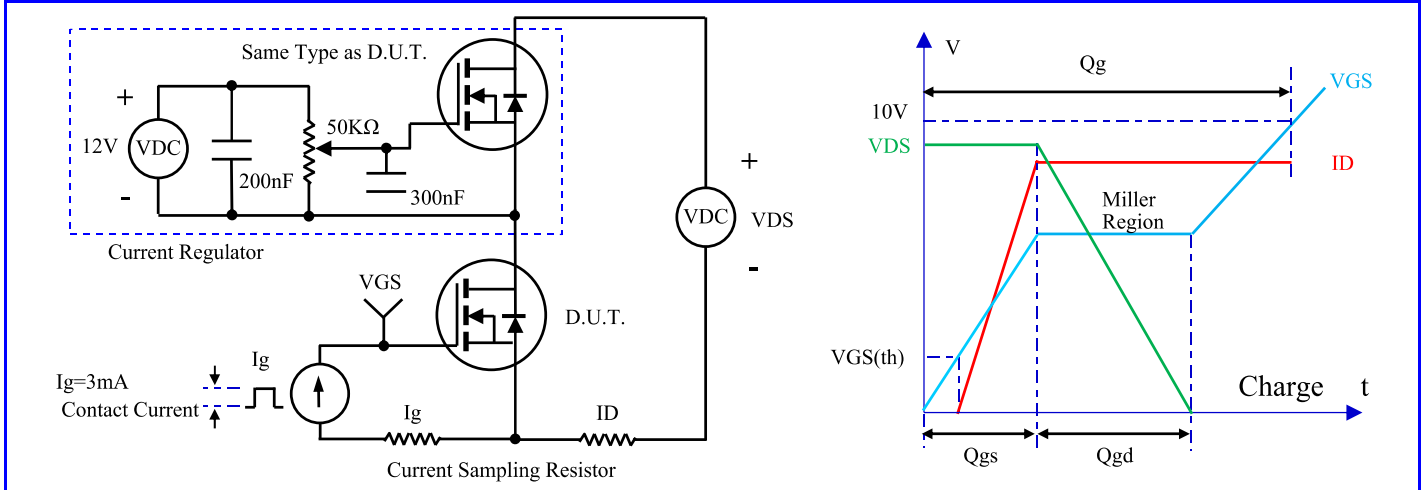


Fig.14- Gate Charge Test Circuit & Waveform

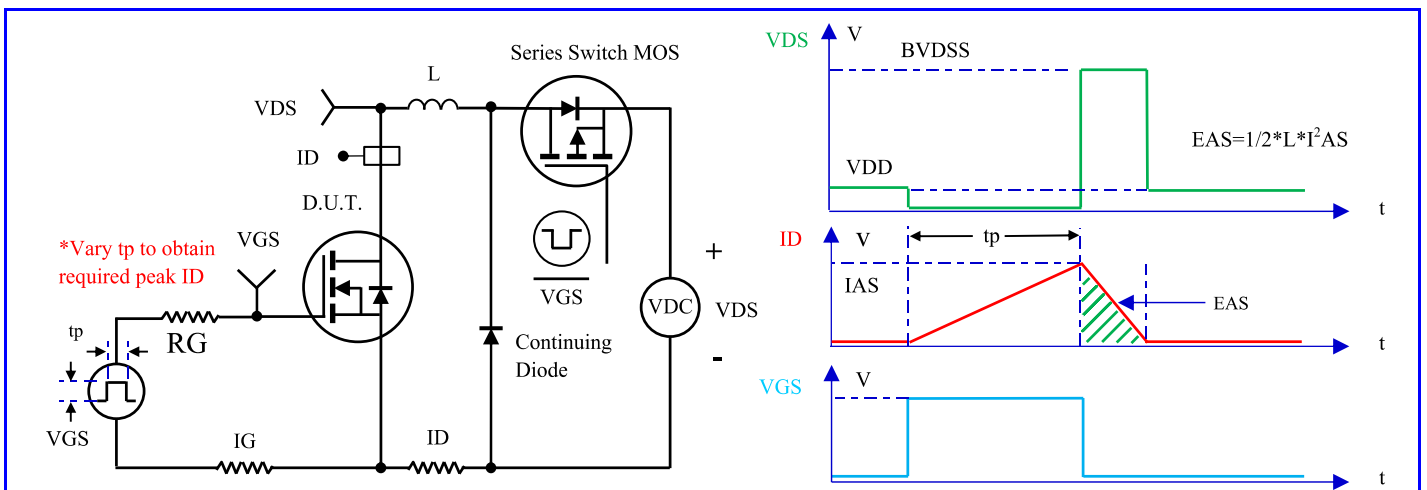


Fig.15- Unclamped Inductive Switching (UIS) Test Circuit & Waveform

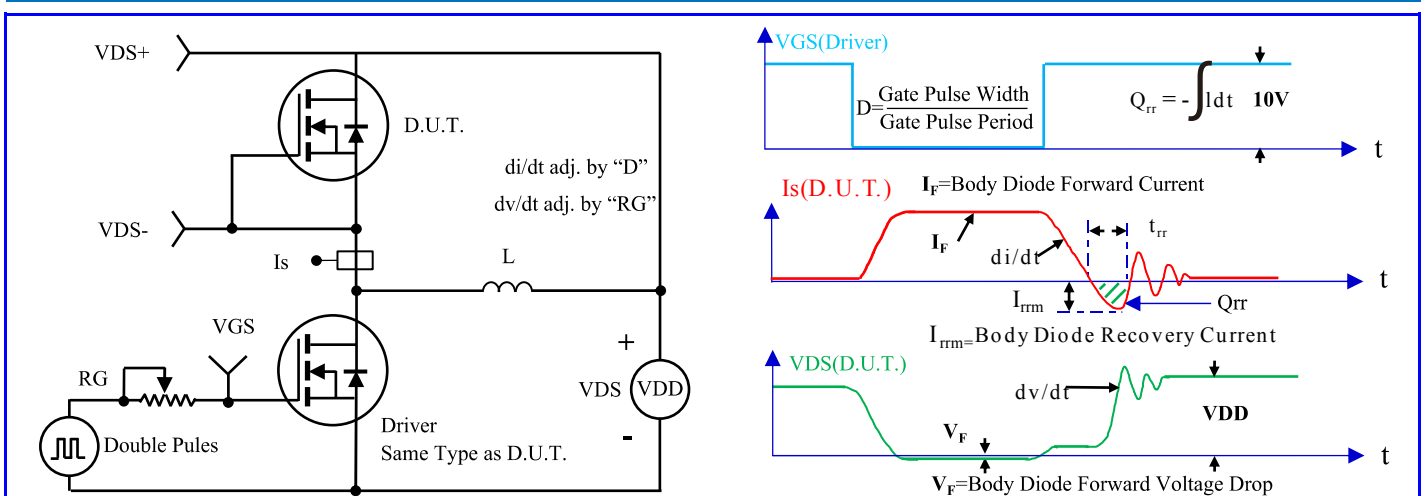


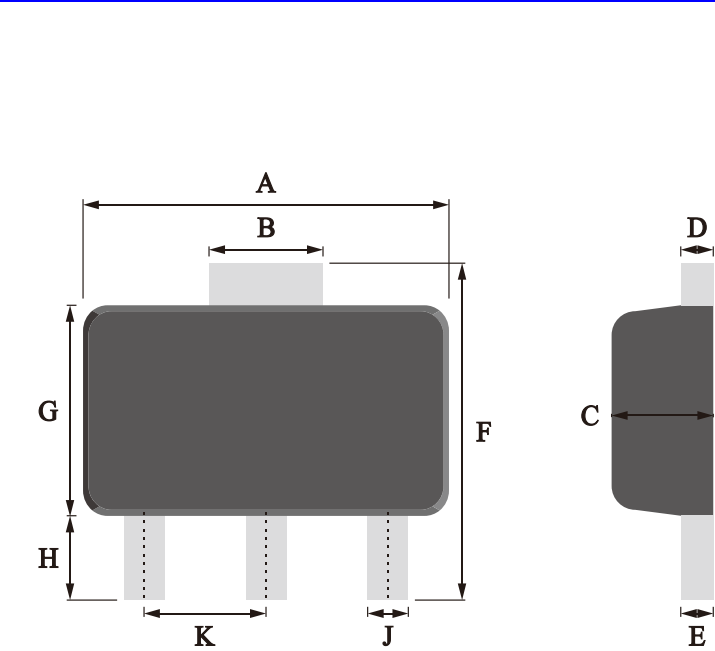
Fig.16- Diode Recovery Test Circuit & Waveform

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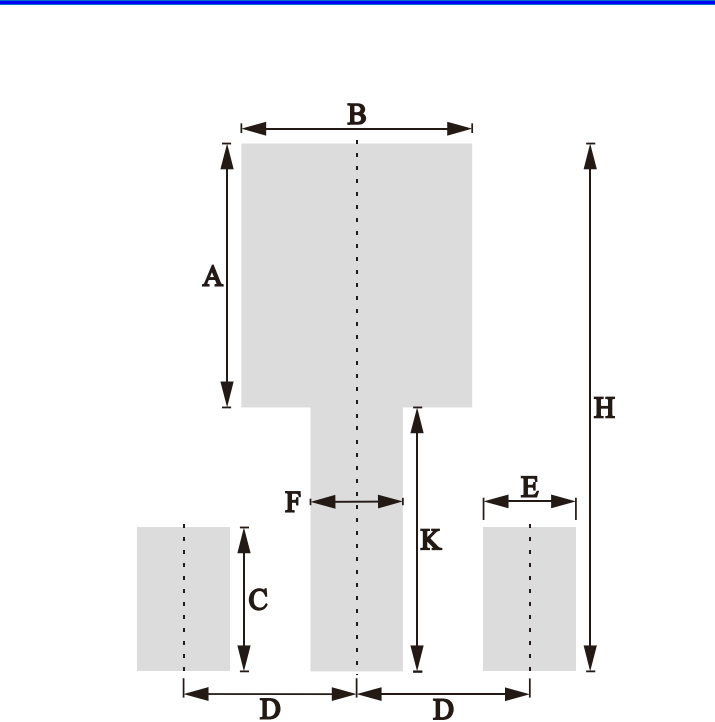
OUTLINE DRAWINGS



SOT-89

OUTLINE DIMENSIONS						
Dim.	Milimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.00	-	5.00	0.1575	-	0.1969
B	1.40	-	1.80	0.0551	-	0.0709
C	1.25	-	1.75	0.0492	-	0.0689
D	0.20	-	0.60	0.0079	-	0.0236
E	0.20	-	0.60	0.0079	-	0.0236
F	3.60	-	4.40	0.1417	-	0.1732
G	2.20	-	2.80	0.0866	-	0.1102
H	0.80	-	1.20	0.0315	-	0.0472
J	0.30	-	0.70	0.0118	-	0.0276
K	1.25	-	1.75	0.0492	-	0.0689

RECOMMEDND LAYOUT DRAWINGS



SOT-89

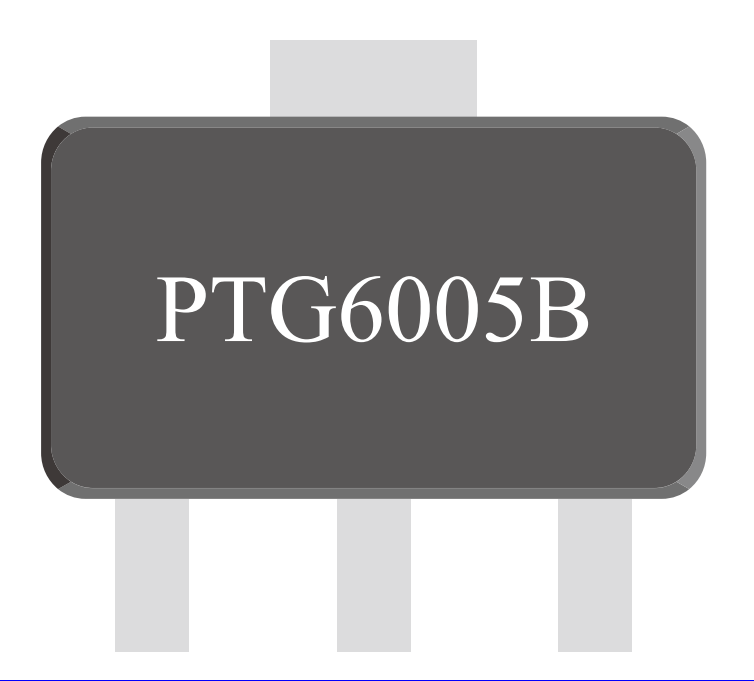
OUTLINE DIMENSIONS						
Dim.	Milimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	2.20	-	-	0.0866	-
B	-	2.00	-	-	0.0787	-
C	-	1.20	-	-	0.0472	-
D	-	1.50	-	-	0.0591	-
E	-	0.80	-	-	0.0315	-
F	-	0.80	-	-	0.0315	-
H	-	47.00	-	-	1.8504	-
K	-	2.20	-	-	0.0866	-

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MARKING INFORMATION



MARKING INSTRUCTIONS

PTG6005B=Model

PACKING INFORMATION

Package Type	Package Code	Product Weight Approx(g/Pcs)	Package Method	Quantity (Pcs/Min. Pack.)	Quantity (Pcs/Inner Box)	Quantity (Pcs/Carton)
SOT-89	P1	0.055	7" Reel	1000	10000	40000

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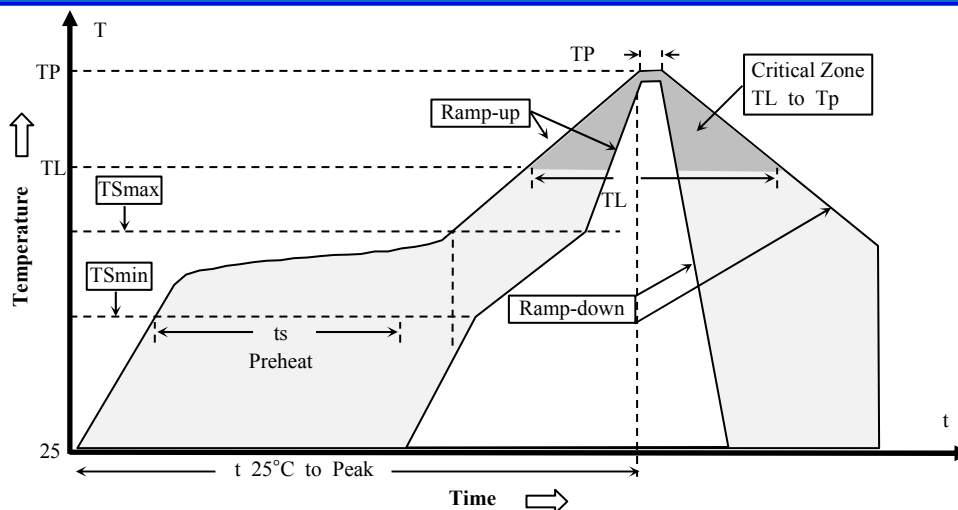


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Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat -Temperature Min(T _S min) -Temperature Max(T _S max) -Time(t _s min to t _s max)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: -Temperature (T _L) - Time (t _L)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

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